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Title of Invention	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking		
Application Number	10/050507		
Date :	2002-01-16		
First Named Applica	Lee Teck		
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Attorney Docket Nur	per: MTI-31607		

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Documents being submitted:	Files	
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	us-ids.dtd	
	us-ids.xsl	
Comments		